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Wu(10) **Pub. No.: US 2014/0061596 A1**(43) **Pub. Date: Mar. 6, 2014**(54) **ORGANIC LIGHT-EMITTING DIODE
DISPLAY PANEL AND MANUFACTURING
METHOD FOR THE SAME****Publication Classification**(51) **Int. Cl.****H01L 27/32** (2006.01)**H01L 33/00** (2006.01)(52) **U.S. Cl.**CPC **H01L 27/3258** (2013.01); **H01L 33/0095**
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§ 371 (c)(1),

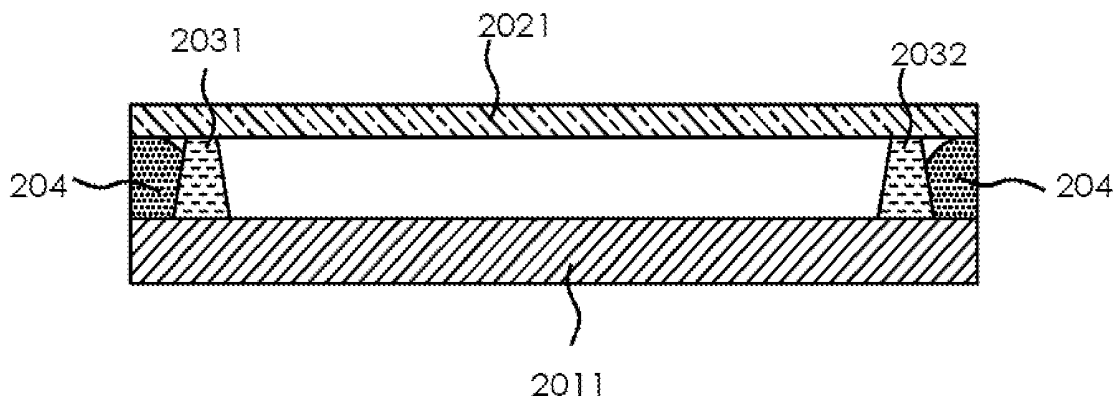
(2), (4) Date: **Dec. 3, 2012**(30) **Foreign Application Priority Data**

Sep. 6, 2012 (CN) 201210327227.8

(57)

ABSTRACT

The present invention discloses an OLED display panel which includes a first TFT array substrate, a first cover and a structural stiffening glue. A first frit and a second frit of the first cover have the structural stiffening glue provided at an outer side thereof, and the structural stiffening glue is in contact with the first TFT array substrate and the first cover. The present invention further discloses a method for manufacturing the OLED display panel. The present invention enables more solid and stable for a structure of the OLED display panel.



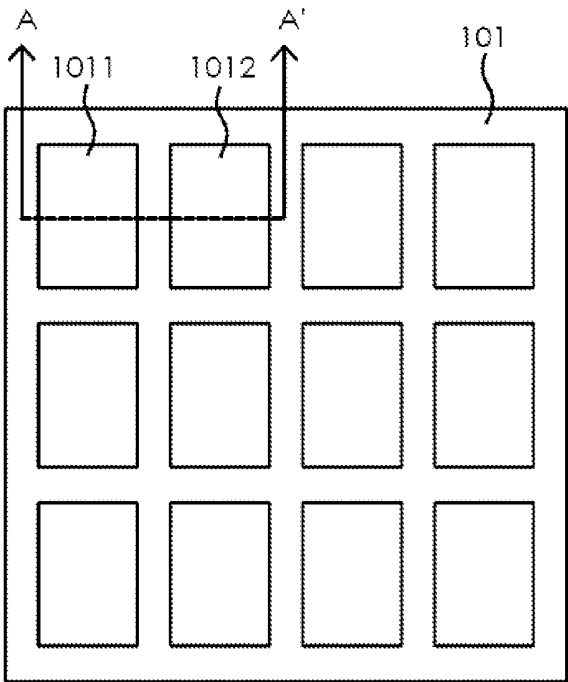


FIG. 1
PRIOR ART

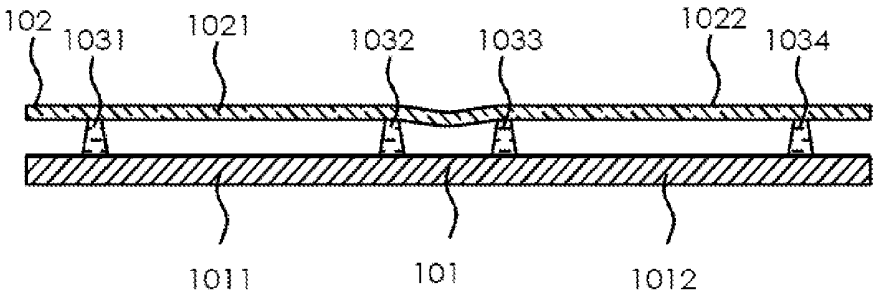


FIG. 2
PRIOR ART

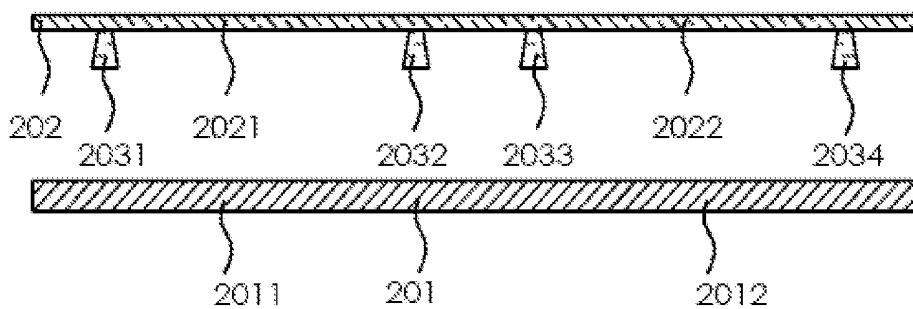


FIG. 3A

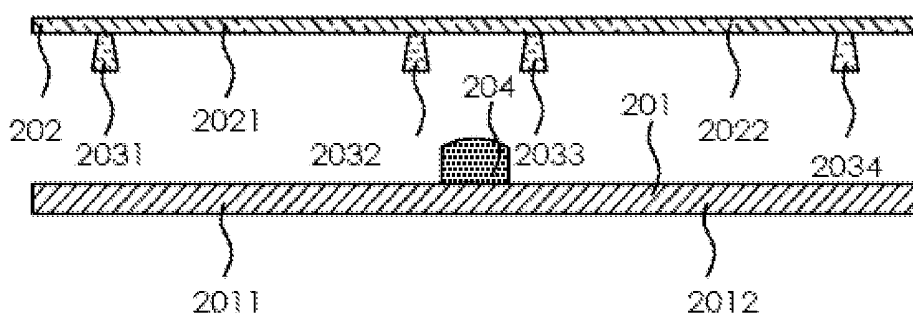


FIG. 3B

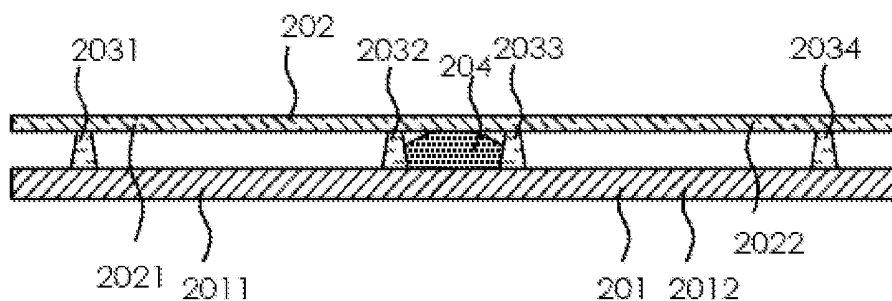


FIG. 3C

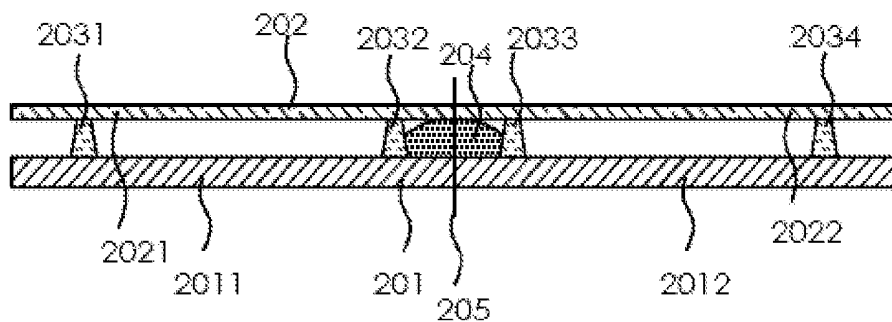


FIG. 3D

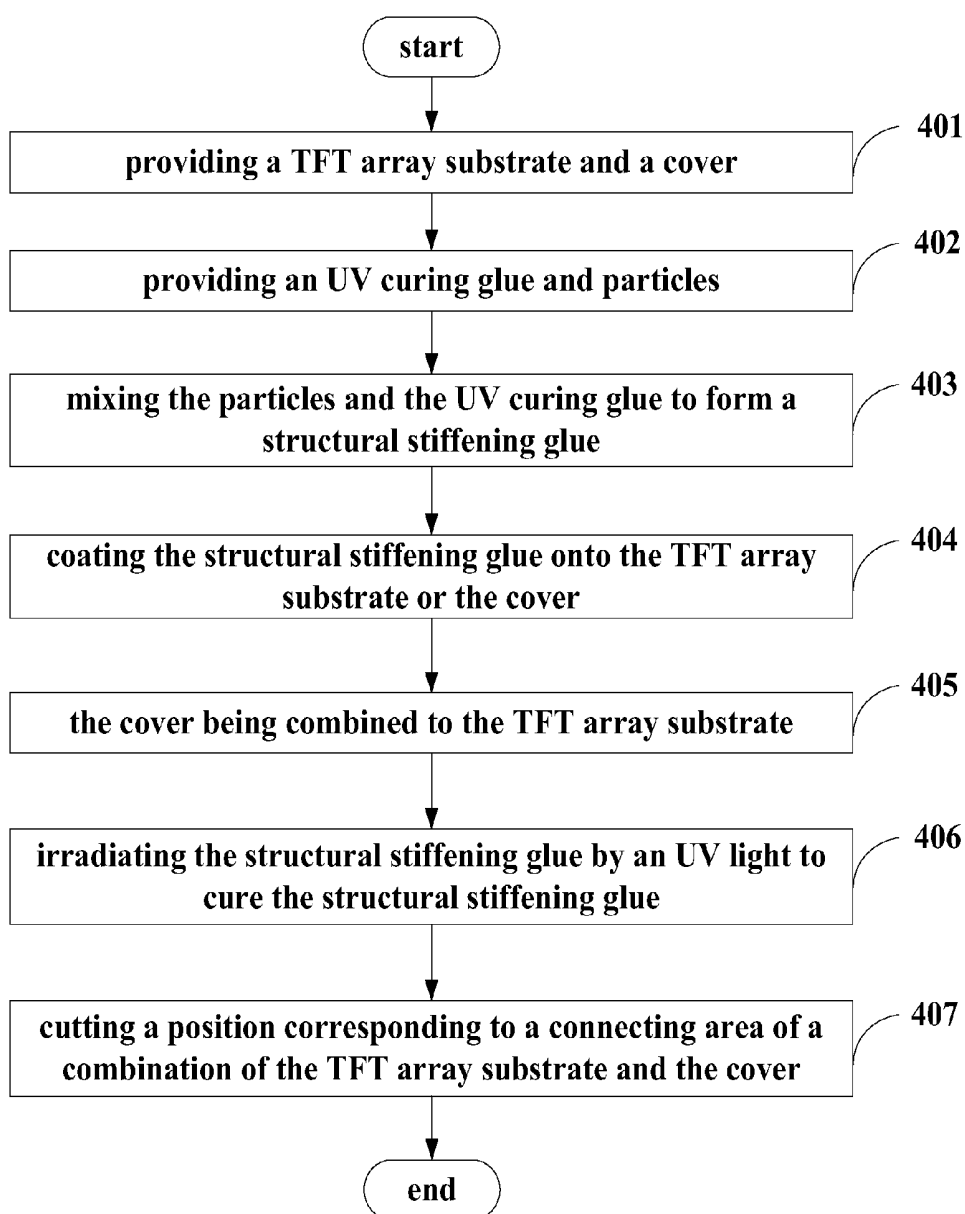


FIG. 4

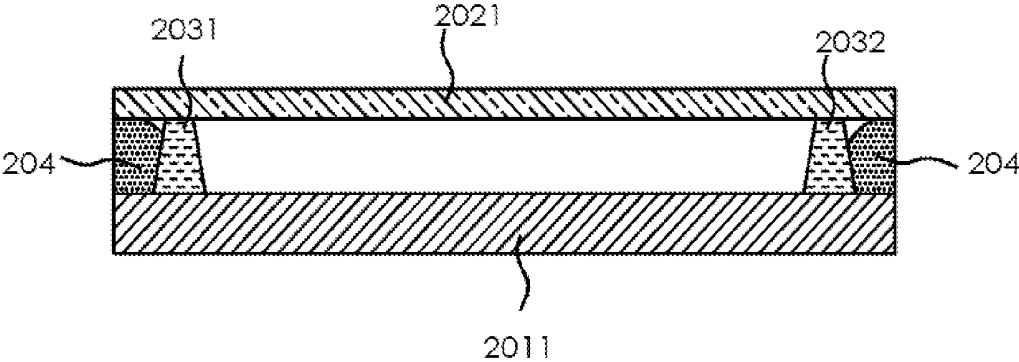


FIG. 5

ORGANIC LIGHT-EMITTING DIODE DISPLAY PANEL AND MANUFACTURING METHOD FOR THE SAME

BACKGROUND OF THE INVENTION

[0001] 1. Field of the Invention

[0002] The present invention relates to a field of organic light-emitting diode (OLED) display technology, and more particularly, to an OLED display panel and a manufacturing method for the same.

[0003] 2. Description of the Prior Art

[0004] In a process of manufacturing a traditional OLED display panel, frits **1031**, **1032**, **1033**, and **1034** are disposed between a thin film transistor (TFT) array substrate **101** and a cover **102**. The frits are first disposed on edges of sub-substrates (including a first TFT array substrate **1011** and a second TFT array substrate **1012**) of the TFT array substrate **101**, respectively. Then, the TFT array substrate **101** is correspondingly arranged with the cover **102** (including a first cover **1021** and a second cover **1022**). Final, a position between two sub-substrates of a combination of the TFT array substrate **101** and the cover **102** is cut.

[0005] In the process of manufacturing the traditional OLED display panel, since the frits are disposed on the edges of two adjacent sub-substrates of the TFT array substrate **101** (as shown in FIGS. **1** and **2**), a spacing is existed between the frits **1032** and **1033** of the two adjacent sub-substrates, and a negative pressure state has existed between the TFT array substrate **101** and the cover **102**. Therefore, after correspondingly arranging the TFT array substrate **101** onto the cover **102**, warpage of the cover **102** or the TFT array substrate **101** will occur, so that the frits disposed between the TFT array substrate **101** and the cover **102** have become a supporting point of the warpage of the cover **102** or the TFT array substrate **101**.

[0006] Further, after cutting the combination of the TFT array substrate **101** and the cover **102**, the warpage of the TFT array substrate **101** or the cover **102**, so that the TFT array substrate **101** is not tightly engaged with the cover **102**. Therefore, a displacement of any one of the TFT array substrate **101** and the cover **102** will easily occur, so that the combination of the TFT array substrate **101** and the cover **102** has less structural strength. Specifically, the frits are sandwiched between the TFT array substrate **101** and the cover **102**. Thus, when a center portion of the TFT array substrate **101** or the cover **102** is pressed, the frits positioned on edges of the TFT array substrate **101** and the cover **102** are often acted as the supporting point, and the edges of the TFT array substrate **101** or the cover **102** will have the warpage around the supporting point, so that a structure of an OLED display panel has not stable, thereby affecting the quality of a finished product of the OLED display panel.

[0007] Therefore, there is a need to provide a new technical scheme, so as to overcome the above-mentioned disadvantages.

SUMMARY OF THE INVENTION

[0008] An object of the present invention is to provide a method for manufacturing an OLED display panel. The present invention is capable of slowing or preventing warpage of a TFT array substrate or a cover, thereby increasing structural strength of a combination of the TFT array substrate and the cover.

[0009] To overcome the above-mentioned disadvantages, the present invention provides a method for manufacturing the OLED display panel, such that the method includes the following steps of:

[0010] (A) providing a TFT array substrate and a cover, the TFT array substrate comprising a first TFT array substrate and a second TFT array substrate, a first connecting area being defined between the first TFT array substrate and the second TFT array substrate, a first frit, a second frit, a third frit and a fourth frit being disposed on the cover, an area between the first frit and the second frit on the cover being aligned to the first TFT array substrate, an area between the third frit and the fourth frit on the cover being aligned to the second TFT array substrate, a second connecting area being defined between the second frit and the third frit on the cover, and a position of the first connecting area being aligned to a position of the second connecting area;

[0011] (B) disposing a structural stiffening glue onto the second connecting area of the cover or the first connecting area of the TFT array substrate, and the structural stiffening glue being applied to strengthen a structure of a combination of the first TFT array substrate and the cover;

[0012] (C) combining the cover onto the TFT array substrate; and

[0013] (D) cutting a predetermined position of the combination of the TFT array substrate and the cover, and the predetermined position being positioned at a position corresponding to the second connecting area,

wherein the step (B) includes the following step of:

[0014] (b1) coating the structural stiffening glue onto the second connecting area of the cover or the first connecting area of the TFT array substrate, so that the structural stiffening glue being in contact with the cover and the TFT array substrate, respectively, when the cover being combined on the TFT array substrate.

[0015] In a method for manufacturing the above OLED display panel, in between the step (C) and the step (D), the method further includes the following step of:

[0016] (E) curing the structural stiffening glue.

[0017] In a method for manufacturing the above OLED display panel, the structural stiffening glue includes an ultra-violet (UV) curing glue, and the step (E) includes the following step of:

[0018] (e1) irradiating the UV curing glue by an UV light, so as to cure the UV curing glue.

[0019] In a method for manufacturing the above OLED display panel, the structural stiffening glue contains particles, and before the step (b1), further including the following steps of:

[0020] (b2) providing the UV curing glue and the particles; and

[0021] (b3) mixing the particles and the UV curing glue.

[0022] In a method for manufacturing the above OLED display panel, the particle is a polyhedron or a sphere.

[0023] Another object of the present invention is to provide a method for manufacturing an OLED display panel. The present invention is capable of slowing or preventing warpage of a TFT array substrate or a cover, thereby increasing structural strength of a combination of the TFT array substrate and the cover.

[0024] To overcome the above-mentioned disadvantages, the present invention provides a method for manufacturing the OLED display panel, such that the method includes the following steps of:

[0025] (A) providing a TFT array substrate and a cover, the TFT array substrate comprising a first TFT array substrate and a second TFT array substrate, a first connecting area being defined between the first TFT array substrate and the second TFT array substrate, a first frit, a second frit, a third frit and a fourth frit being disposed on the cover, an area between the first frit and the second frit on the cover being aligned to the first TFT array substrate, an area between the third frit and the fourth frit on the cover being aligned to the second TFT array substrate, a second connecting area being defined between the second frit and the third frit on the cover, and a position of the first connecting area being aligned to a position of the second connecting area;

[0026] (B) disposing a structural stiffening glue onto the second connecting area of the cover or the first connecting area of the TFT array substrate;

[0027] (C) combining the cover onto the TFT array substrate; and

[0028] (D) cutting a predetermined position of the combination of the TFT array substrate and the cover, and the predetermined position being positioned at a position corresponding to the second connecting area.

[0029] In a method for manufacturing the above OLED display panel, such that step (B) includes the following step of:

[0030] (b1) coating the structural stiffening glue onto the second connecting area of the cover or the first connecting area of the TFT array substrate, so that the structural stiffening glue being in contact with the cover and the TFT array substrate, respectively, when the cover being combined on the TFT array substrate.

[0031] In a method for manufacturing the above OLED display panel, in between the step (C) and the step (D), the method further includes the following step of:

[0032] (E) curing the structural stiffening glue.

[0033] In a method for manufacturing the above OLED display panel, the structural stiffening glue includes an ultra-violet (UV) curing glue, and the step (E) includes the following step of:

[0034] (e1) irradiating the UV curing glue by an UV light, so as to cure the UV curing glue.

[0035] In a method for manufacturing the above OLED display panel, the structural stiffening glue contains particles, and before the step (b1), further including the following steps of:

[0036] (b2) providing the UV curing glue and the particles; and

[0037] (b3) mixing the particles and the UV curing glue.

[0038] In a method for manufacturing the above OLED display panel, the particle is a polyhedron or a sphere.

[0039] A further another object of the present invention is to provide an OLED display panel. The present invention is capable of slowing or preventing warpage of a TFT array substrate or a cover, thereby increasing structural strength of a combination of the TFT array substrate and the cover.

[0040] To overcome the above-mentioned disadvantages, the present invention provides the OLED display panel which includes:

[0041] a first TFT array substrate;

[0042] a first cover being disposed on the first TFT array substrate, a first frit and a second frit being disposed on the first cover, and an area between the first frit and the second frit on the first cover being aligned to the first TFT array substrate; and

[0043] a structural stiffening glue being disposed at an outer side of the first frit and the second frit of the first cover, and the structural stiffening glue being in contact with the first TFT array substrate and the first cover.

[0044] In the above OLED display panel, the structural stiffening glue is a mixture of an UV curing glue and particles.

[0045] In the above OLED display panel, the particle is a polyhedron or a sphere.

[0046] In the above OLED display panel, the material of the particle is glass.

[0047] In the present invention, since the structural stiffening glue is disposed on the first connecting area of the TFT array substrate or the second connecting area of the cover, and therefore the structural stiffening glue can play a role of connection or support with regard to the TFT array substrate and the cover. Moreover, after a combination of the TFT array substrate and the cover, a space corresponding to the first connecting area or the second connecting area is partially or completely filled with the structural stiffening glue, so as to increase air pressure of the space which is in a negative pressure state, thereby slowing and perhaps even preventing the warpage of the TFT array substrate or the cover caused by the negative pressure state between the TFT array substrate and the cover.

[0048] Moreover, since the warpage of the TFT array substrate or the cover is slowed or prevented, and therefore the TFT array substrate and the cover can have more contacting area with frits (including the first frit, the second frit, the third frit and the fourth frit), that is, the TFT array substrate and the cover can more fully flattened on the frits to increase an effective area of the frits cured by a laser, so that a structure of a combination of the TFT array substrate, the cover and the frits has more solid.

[0049] Moreover, the structural stiffening glue is capable of strengthening a structure of the OLED display panel. When a center portion of the cover is pressed, the structural stiffening glue is capable of applying a pulling force at an edge of the cover to prevent the warpage of the cover, so that the structure of the OLED display panel of the present invention is more stable.

[0050] Since the structural stiffening glue contains the particles, the particles and the UV curing glue are mixed, and therefore the structural stiffening glue has more cohesive force and strength after curing, that advantages to improve a life span of the structural stiffening glue, thereby improving a life span of the OLED display panel of the present invention.

[0051] The above objectives, other objectives, features, advantages and embodiments of the present invention will be better understood from the following description being considered in connection with the accompanied drawings and in which a preferred embodiment of the invention is illustrated by way of example.

BRIEF DESCRIPTION OF THE DRAWINGS

[0052] FIG. 1 is a schematic view of a traditional OLED display panel before cutting arrays;

[0053] FIG. 2 is a schematic view of a cross-section A-A' of FIG. 1;

[0054] FIGS. 3A, 3B, 3C and 3D are schematic views of a method according to the present invention for manufacturing an OLED display panel;

[0055] FIG. 4 is a flow chart of a method according to the present invention for manufacturing the OLED display panel; and

[0056] FIG. 5 is a schematic view of a structure of the OLED display panel according to the present invention.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0057] In the following detailed description of the preferred embodiments, reference is made to the accompanying drawings which form a part hereof, and in which is shown by way of illustration specific embodiments in which the invention may be practiced.

[0058] Please refer to FIGS. 3A, 3B, 3C, 3D and 4, wherein FIGS. 3A, 3B, 3C and 3D are schematic views of a method according to the present invention for manufacturing an OLED display panel, and FIG. 4 is a flow chart of a method according to the present invention for manufacturing the OLED display panel.

[0059] In step 401, a TFT array substrate 201 and a cover 202 are provided. The TFT array substrate 201 includes a plurality of sub-TFT array substrate, such as a first TFT array substrate 2011 and a second TFT array substrate 2012. A first connecting area is defined between the first TFT array substrate 2011 and the second TFT array substrate 2012. A first frit 2031, a second frit 2032, a third frit 2033 and a fourth frit 2034 are disposed on the cover 202. An area between the first frit 2031 and the second frit 2032 on the cover 202 is aligned to the first TFT array substrate 2011. An area between the third frit 2033 and the fourth frit 2034 on the cover 202 is aligned to the second TFT array substrate 2012. A second connecting area being defined between the second frit 2032 and the third frit 2033 on the cover 202. A position of the first connecting area is aligned to a position of the second connecting area.

[0060] In step 402 to step 403, a structural stiffening glue 204 is provided. The structural stiffening glue 204 is applied to strengthen a structure of a combination of the TFT array substrate 201 and the cover 202. Specifically, in the step 402, an UV curing glue and particles are provided. The particles have less impurities to enable the structural stiffening glue 204 having more cohesive force and strength, so that the structure of the combination of the TFT array substrate 201 and the cover 202 has more solid. In the step 403, the particles and the UV curing glue are mixed to form the structural stiffening glue. Specifically, the UV curing glue and the particles are sufficiently mixed, so that the particles are uniformly distributed in the UV curing glue. The particle can be a polyhedron or a sphere. The material of the particle can be glass.

[0061] In step 404, the structural stiffening glue 204 is disposed on the second connecting area of the cover 202 or the first connecting area of the TFT array substrate 201. Specifically, the structural stiffening glue 204 is coated on the second connecting area of the cover 202 or the first connecting area of the TFT array substrate 201, and the structural stiffening glue 204 coated on the second connecting area of the cover 202 or the first connecting area of the TFT array substrate 201 have sufficient amounts of the structural stiffening glue 204, so that the structural stiffening glue 204 is in contact with the cover 202 and the TFT array substrate 201, respectively, when the cover 202 is combined on the TFT array substrate 201.

[0062] In step 405, the cover 202 is combined to the TFT array substrate 201.

[0063] In step 406, the structural stiffening glue is cured. Specifically, in step 406, the structural stiffening glue 204 is

irradiated by an UV light, so that the UV curing glue within the structural stiffening glue 204 is cured.

[0064] In step 407, a predetermined position of the combination of the TFT array substrate 201 and the cover 202 is cut. The predetermined position is positioned at a position corresponding to the second connecting area. Please refers to FIG. 3, the predetermined position is a position of a straight line within FIG. 3.

[0065] In the above-mentioned method, since the structural stiffening glue 204 is disposed on the first connecting area of the TFT array substrate 201 or the second connecting area of the cover 202, and therefore the structural stiffening glue 204 can play a role of connection or support with regard to the TFT array substrate 201 and the cover 202. Moreover, after a combination of the TFT array substrate 201 and the cover 202, a space corresponding to the first connecting area or the second connecting area is partially or completely filled with the structural stiffening glue 204, so as to increase air pressure of the space which is in a negative pressure state, thereby slowing and perhaps even preventing warpage of the TFT array substrate 201 or the cover 202 caused by the negative pressure state between the TFT array substrate 201 and the cover 202.

[0066] Moreover, since the warpage of the TFT array substrate 201 or the cover 202 is slowed or prevented, and therefore the TFT array substrate 201 and the cover 202 can have more contacting area with frits (including the first frit 2031, the second frit 2032, the third frit 2033 and the fourth frit 2034), that is, the TFT array substrate 201 and the cover 202 can more fully flattened on the frits to increase an effective area of the frits cured by a laser, so that a structure of a combination of the TFT array substrate 201, the cover 202 and the frits has more solid.

[0067] Please refer to FIG. 5. FIG. 5 is a schematic view of a structure of the OLED display panel according to the present invention. The OLED display panel according to the present invention includes the first TFT array substrate 2011, a first cover 2021 and the structural stiffening glue 204. The first cover 2021 is disposed on the first TFT array substrate 2011, the first frit 2031 and the second frit 2032 are disposed on the first cover 2021, and the area between the first frit 2031 and the second frit 2032 on the first cover 2021 is aligned to the first TFT array substrate 2011. The structural stiffening glue 204 is disposed at an outer side of the first frit 2031 and the second frit 2032 of the first cover 2021, and the structural stiffening glue 204 coated on an edge of the outer side of the first frit 2031 and the second frit 2032 of the first cover 2021 have sufficient amounts of the structural stiffening glue 204, so that the structural stiffening glue 204 is in contact with the first TFT array substrate 2011 and the first cover 2021, respectively, when the first cover 2021 is combined on the first TFT array substrate 2011. The structural stiffening glue 204 is applied to strengthen a structure of a combination of the first TFT array substrate 2011 and the first cover 2021. The structural stiffening glue 204 is a mixture of the UV curing glue and the particles. The particles have less impurities to enable the structural stiffening glue 204 having more cohesive force and strength, so that the structure of the combination of the first TFT array substrate 2011 and the first cover 2021 has more solid. The particles are uniformly distributed in the UV curing glue. The particle can be the polyhedron or the sphere. The material of the particle can be glass.

[0068] However, since the structural stiffening glue 204 is sandwiched between the first TFT array substrate 2011 and

the first cover **2021** of the OLED display panel of the present invention, the structural stiffening glue **204** is positioned at the edge of the outer side of the first frit **2031** and the second frit **2032** of the first cover **2021**, and the structural stiffening glue **204** is in contact with the first TFT array substrate **2011** and the first cover **2021**, respectively. Therefore, the structural stiffening glue **204** is capable of strengthening the structure of the OLED display panel. Specifically, when a center portion of the first cover **2021** is pressed, the structural stiffening glue **204** is capable of applying a pulling force at an edge of the first cover **2021** to prevent the warpage of the first cover **2021**, so that the structure of the OLED display panel of the present invention is more stable.

[0069] Moreover, since the warpage of the first TFT array substrate **2011** or the first cover **2021** is prevented, and therefore the first TFT array substrate **2011** and the first cover **2021** can have more contacting area with the frits, that is, the first TFT array substrate **2011** and the first cover **2021** can more fully flattened on the frits to increase the effective area of the frits cured by the laser, so that a structure of a combination of the first TFT array substrate **2011**, the first cover **2021** and the frits has more solid.

[0070] Moreover, since the structural stiffening glue **204** contains the UV curing glue, and therefore the UV curing glue is irradiated just by the UV light to cure the UV curing glue in a process for manufacturing the OLED display panel of the present invention, that is, the structural stiffening glue **204** is cured, thereby advantages to reduce manufacturing time of the OLED display panel of the present invention.

[0071] Since the structural stiffening glue **204** contains the particles, the particles and the UV curing glue are mixed, and therefore the structural stiffening glue **204** has more cohesive force and strength after curing, that advantages to improve a life span of the structural stiffening glue **204**, thereby improving a life span of the OLED display panel of the present invention.

[0072] It should be understood, however, that even though numerous characteristics and advantages of the present invention have been set forth in the foregoing description, together with details of the structure and function of the invention, the disclosure is illustrative only, and changes may be made in detail, especially in matters of shape, size, and arrangement of parts within the principles of the invention to the full extent indicated by the broad general meaning of the terms in which the appended claims are expressed.

What is claimed is:

1. A method for manufacturing an organic light-emitting diode (OLED) display panel, the method comprising steps of:

- (A) providing a thin film transistor (TFT) array substrate and a cover, the TFT array substrate comprising a first TFT array substrate and a second TFT array substrate, a first connecting area being defined between the first TFT array substrate and the second TFT array substrate, a first frit, a second frit, a third frit and a fourth frit being disposed on the cover, an area between the first frit and the second frit on the cover being aligned to the first TFT array substrate, an area between the third frit and the fourth frit on the cover being aligned to the second TFT array substrate, a second connecting area being defined between the second frit and the third frit on the cover, and a position of the first connecting area being aligned to a position of the second connecting area;
- (B) disposing a structural stiffening glue onto the second connecting area of the cover or the first connecting area

of the TFT array substrate, and the structural stiffening glue being applied to strengthen a structure of a combination of the first TFT array substrate and the cover;

(C) combining the cover onto the TFT array substrate; and

(D) cutting a predetermined position of the combination of the TFT array substrate and the cover, and the predetermined position being positioned at a position corresponding to the second connecting area, wherein the step (B) includes the following step of:

(b1) coating the structural stiffening glue onto the second connecting area of the cover or the first connecting area of the TFT array substrate, so that the structural stiffening glue being in contact with the cover and the TFT array substrate, respectively, when the cover being combined on the TFT array substrate.

2. The method for manufacturing an OLED display panel of claim 1, wherein in between the step (C) and the step (D), the method further comprises the following step of:

(E) curing the structural stiffening glue.

3. The method for manufacturing an OLED display panel of claim 2, wherein the structural stiffening glue comprises an ultraviolet (UV) curing glue, and the step (E) comprises the following step of:

(e1) irradiating the UV curing glue by an UV light, so as to cure the UV curing glue.

4. The method for manufacturing an OLED display panel of claim 3, wherein the structural stiffening glue contains particles, and before the step (b1), further comprising the following steps of:

(b2) providing the UV curing glue and the particles; and

(b3) mixing the particles and the UV curing glue.

5. The method for manufacturing an OLED display panel of claim 4, wherein the particle is a polyhedron or a sphere.

6. A method for manufacturing an organic light-emitting diode (OLED) display panel, the method comprising steps of:

(A) providing a thin film transistor (TFT) array substrate and a cover, the TFT array substrate comprising a first TFT array substrate and a second TFT array substrate, a first connecting area being defined between the first TFT array substrate and the second TFT array substrate, a first frit, a second frit, a third frit and a fourth frit being disposed on the cover, an area between the first frit and the second frit on the cover being aligned to the first TFT array substrate, an area between the third frit and the fourth frit on the cover being aligned to the second TFT array substrate, a second connecting area being defined between the second frit and the third frit on the cover, and a position of the first connecting area being aligned to a position of the second connecting area;

(B) disposing a structural stiffening glue onto the second connecting area of the cover or the first connecting area of the TFT array substrate;

(C) combining the cover onto the TFT array substrate; and

(D) cutting a predetermined position of the combination of the TFT array substrate and the cover, and the predetermined position being positioned at a position corresponding to the second connecting area.

7. The method for manufacturing an OLED display panel of claim 6, wherein the step (B) comprises the following step of:

(b1) coating the structural stiffening glue onto the second connecting area of the cover or the first connecting area of the TFT array substrate, so that the structural stiffening glue being in contact with the cover and the TFT

array substrate, respectively, when the cover being combined on the TFT array substrate.

8. The method for manufacturing an OLED display panel of claim **7**, wherein in between the step (C) and the step (D), the method further comprises the following step of:

(E) curing the structural stiffening glue.

9. The method for manufacturing an OLED display panel of claim **8**, wherein the structural stiffening glue comprises an ultraviolet (UV) curing glue, and the step (E) comprises the following step of:

(e1) irradiating the UV curing glue by an UV light, so as to cure the UV curing glue.

10. The method for manufacturing an OLED display panel of claim **9**, wherein the structural stiffening glue contains particles, and before the step (b1), further comprising the following steps of:

(b2) providing the UV curing glue and the particles; and

(b3) mixing the particles and the UV curing glue.

11. The method for manufacturing an OLED display panel of claim **10**, wherein the particle is a polyhedron or a sphere.

12. An organic light-emitting diode (OLED) display panel, comprising:

a first thin film transistor (TFT) array substrate;

a first cover being disposed on the first TFT array substrate, a first frit and a second frit being disposed on the first cover, and an area between the first frit and the second frit on the first cover being aligned to the first TFT array substrate; and

a structural stiffening glue being disposed at an outer side of the first frit and the second frit of the first cover, and the structural stiffening glue being in contact with the first TFT array substrate and the first cover.

13. The OLED display panel of claim **12**, wherein the structural stiffening glue is a mixture of an ultraviolet (UV) curing glue and particles.

14. The OLED display panel of claim **13**, wherein the particle is a polyhedron or a sphere.

15. The OLED display panel of claim **14**, wherein the material of the particle is glass.

* * * * *

专利名称(译)	有机发光二极管显示面板及其制造方法		
公开(公告)号	US20140061596A1	公开(公告)日	2014-03-06
申请号	US13/701813	申请日	2012-10-12
[标]申请(专利权)人(译)	吴泰PI		
申请(专利权)人(译)	吴 , TAI-PI		
当前申请(专利权)人(译)	深圳市中国星光电科技有限公司.		
[标]发明人	WU TAI PI		
发明人	WU, TAI-PI		
IPC分类号	H01L27/32 H01L33/00		
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摘要(译)

本发明公开了一种OLED显示面板，包括第一TFT阵列基板，第一盖板和结构加强胶。第一玻璃料的第一玻璃料和第二玻璃料具有设置在其外侧的结构硬化胶，并且结构硬化胶与第一TFT阵列基板和第一盖接触。本发明还公开了一种制造OLED显示面板的方法。本发明使得OLED显示面板的结构更加牢固和稳定。

